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Korthuis et al.(10) **Pub. No.: US 2023/0230790 A1**(43) **Pub. Date: Jul. 20, 2023**(54) **UNSUPPORTED TOP HAT LAYERS IN
PRINthead DIES**(71) Applicant: **Hewlett-Packard Development
Company, L.P.**, Spring, TX (US)(72) Inventors: **Vincent C. Korthuis**, Corvallis, OR
(US); **Huyen Pham**, Corvallis, OR
(US); **Tsuyoshi Yamashita**, Corvallis,
OR (US)(73) Assignee: **Hewlett-Packard Development
Company, L.P.**, Spring, TX (US)(21) Appl. No.: **18/123,134**(22) Filed: **Mar. 17, 2023****Related U.S. Application Data**(63) Continuation of application No. 17/414,413, filed on
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2085/0291 (2013.01)(57) **ABSTRACT**

In example implementations, a printhead die is provided. The printhead die includes a substrate, a chamber layer formed on the substrate, a plurality of printing fluid ejection chambers coupled to opposite sides of the chamber layer and along a length of the chamber layer, and a top hat layer formed on the chamber layer and the plurality of printing fluid ejection chambers. The chamber layer includes a void to store printing fluid. The top hat layer includes an initial unsupported top hat layer portion over the void, wherein the initial unsupported top hat layer portion comprises a first end that is narrower than a second end.

